



IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,
Assemblies, Related Materials and Processes
For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 13.0001

CB Certificate No.: 030/ICA

Schedule Number: IECQ-C BSI 13.0001-S

Rev No.: 4

Revision Date: 2020/12/24

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Board Types: Rigid Multilayer (Type 4) IPC 6012C Class 3*

Rigid double-sided with plated through holes (Type 2)
Rigid single & double-sided with plain holes (Types 1 & 2)
Double-Sided boards (Type 2)
Single-Sided Boards (Type 1 & 2)

Flex-Rigid multilayer with through holes (Type 4) IPC 6013B Class 3*

*With reduced sampling for structural integrity (micro-section) in accordance with IECQ OD 301

Base Materials: Epoxide Woven Glass (IPC4101, 4202, 4203, BS4584)
Polyimide film/polyester film (IPC 4204)
Polytetrafluorethylene (IPC 4103)

Board Size: 495.30 mm x 419.10 mm single/double and multilayer
261.87 mm x 322.33 mm flex-rigid multilayer

Number of Layers: 32 maximum Rigid multilayer
10 maximum Flex-Rigid multilayer

Conductors: 0.050 mm (photomech) Tolerance -0.01+0.03mm
0.10 mm (photomech) Tolerance -0.02 +0.03 mm

Plated-through Hole Diameter: 0.20 mm Minimum Finished hole size
0.80 mm Minimum Finished hole size

Aspect Ratio: 20 : 1 Maximum single and double sided
16.0:1 Maximum multilayer
2.27 : 1 Maximum flex-rigid multilayer

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Finishes: * Hot Air Solder Levelling
 Immersion Silver
 2.5µm Gold over Copper Edge Contacts
 Liquid Photopolymer Solder Resist
 Legend; UV or Oven Cured
 Solder resist UV cured

Additional: Selective Electroplated Gold (2.5 µm) on Copper
 Selective Electroless Gold (0.05 µm) on Copper
 Silver, Organic Coating
 NemaL1-I

* This finish meets the solderability requirements.

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